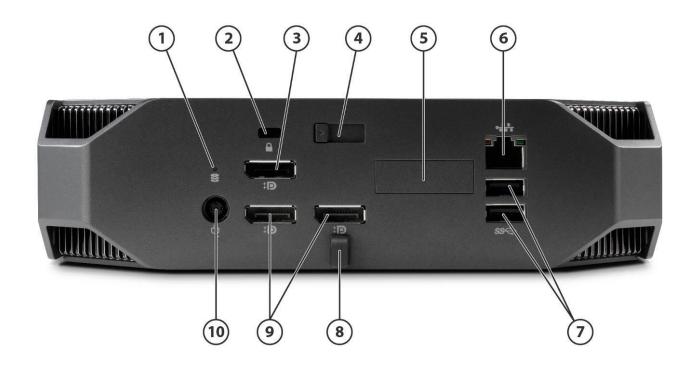
HP Z2 Mini Workstation



Front View

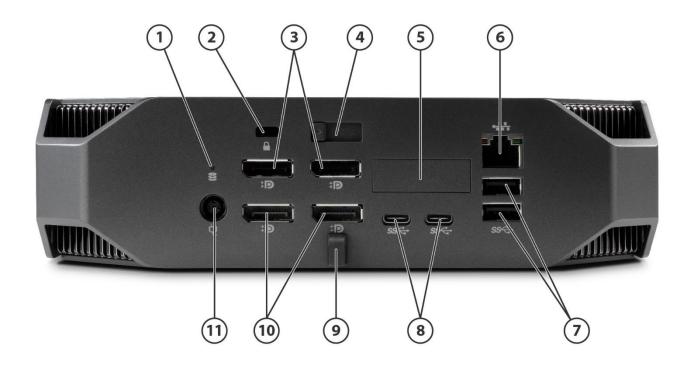
- 1. Power Button
- 2. Headset
- 3. USB 3.0 charging data port
- 4. USB 3.0 data port



HP Z2 Mini Entry, back view

- 1. HDD LED
- 2. Security slot
- 3. (1) DisplayPort™
- 4. Cover latch
- 5. Serial port (optional)

- 6. RJ-45 (Ethernet)
- 7. (2) USB 3.0 ports
- 8. DC cable clip
- 9. (2) DisplayPort™
- 10. DC In

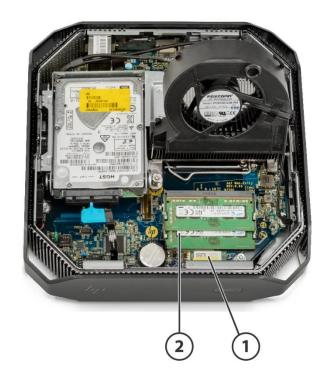


HP Z2 Mini Performance, back view

- 1. HDD LED
- 2. Security slot
- 3. (2) DisplayPort™
- 4. Cover latch
- 5. Serial port (optional)
- 6. RJ-45 (Ethernet)

- 7. (2) USB 3.0 ports
- 8. (2) USB Type C™
- 9. DC cable clip
- 10. (2) DisplayPort™
- 11. DC In





HP Z2 Mini Entry, Internal View

- 1. SATA HDD/SSD (9.5mm 2.5")
- 2. CPU heatsink
- 3. CPU blower
- 4. M.2 80mm (PCIe SSD)

- 1. M.2 30mm WLAN/BT
- 2. (2) SODIMM memory slots







HP Z2 Mini Performance, Internal View

- 1. SATA HDD/SSD (9.5mm 2.5")
- 2. CPU heatsink
- 3. CPU blower
- 4. M.2 80mm (PCIe SSD)

- 1. GPU heatsink (underneath HDD/SSD cage)
- 2. M.2 30mm WLAN/BT
- 3. (2) SODIMM memory slots
- 4. GPU blower



HP Z2 Mini, bottom view

Removable bottom feet for access to integrated VESA mounting holes

Overview

Form Factor Operating Systems

Mini Form Factor

Preinstalled:

- Windows 10 Pro 64¹
- Windows 10 Pro License MSNA¹
- Windows 7 Professional 64 (available through downgrade rights from Windows 10 Pro)²
- HP Linux® -ready
- Red Hat® Enterprise Linux Workstation (1 year paper license available; Preinstall not available)

Supported:

- Red Hat® Enterprise Linux Desktop 6.7, 7.2
- SUSE Linux® Enterprise Desktop 11 SP4, 12 SP1

Notes: For detailed OS/hardware support information for Linux, see:

http://www.hp.com/support/linux_hardware_matrix

- Not all features are available in all editions or versions of Windows. Systems may require
 upgraded and/or separately purchased hardware, drivers, software or BIOS update to take
 full advantage of Windows functionality. Windows 10 is automatically updated, which is
 always enabled. ISP fees may apply and additional requirements may apply over time for
 updates. See http://www.windows.com
- 2. This system is preinstalled with Windows 7 Professional software and also comes with a license and media for Windows 10 Pro software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.



Overview

Processors*

Name	Cores	Clock Speed (GHz)	Intel® Turbo Boost Technology¹	Cache (MB)	Memory Speed (MT/s)	Hyper- Threading	Integrated Graphics	Featuring Intel® vPro™ Technology	TDP (W)
			Z2 Mini	G3 Perfo	rmance bas	e unit			
ntel® Xeon® processor E3-1245v6	4	3.7	4.1	8	2400	Y	Intel® HD Graphics P630	Y	80W
ntel® Xeon® processor 3-1225v6	4	3.3	3.7	8	2400	N	Intel® HD Graphics P630	Y	80W
ntel® Xeon® processor 3-1205v6	4	3.0	N/A	8	2400	N	Intel® HD Graphics P630	Y	65W
ntel® Xeon® processor 3-1245v5	4	3.5	3.9	8	2133	Y	Intel® HD Graphics P530	Y	80W
ntel® Xeon® processor 3-1225v5	4	3.3	3.7	8	2133	N	Intel® HD Graphics P530	Y	80W
ntel® Core™ i7-7700 rocessor	4	3.6	4.2	8	2400	Y	Intel® HD Graphics 630	Y	65W
ntel® Core™ i5-7500 processor	4	3.4	3.8	6	2400	N	Intel® HD Graphics 630	Y	65W
ntel® Core™ i3-7100 rocessor	2	3.9	N/A	3	2400	N	Intel® HD Graphics 630	N	51W
ntel® Core™ i7-6700 processor	4	3.4	4.0	8	2133	Y	Intel® HD Graphics 530	Y	65W
ntel® Core™ i5-6500 processor	4	3.2	3.6	6	2133	N	Intel® HD Graphics 530	Y	65W
Intel® Core™ i3-6100 processor	2	3.7	N/A	3	2133	N	Intel® HD Graphics 530	N	51W
			Z2 l	Mini G3 E	ntry base ui	nit			
ntel® Xeon® processor 3-1205v6	4	3.0	N/A	8	2400	N	Intel® HD Graphics P630	Y	65W
ntel® Core™ i7-7700 processor	4	3.6	4.2	8	2400	Y	Intel® HD Graphics 630	Y	65W
ntel® Core™ i5-7500 Processor	4	3.4	3.8	6	2400	N	Intel® HD Graphics 630	Υ	65W
ntel® Core™ i3-7100 processor	2	3.9	N/A	3	2400	N	Intel® HD Graphics 630	N	51W
ntel® Core™ i7-6700 processor	4	3.4	4.0	8	2133	Y	Intel® HD Graphics 530	Υ	65W
ntel® Core™ i5-6500 rocessor	4	3.2	3.6	6	2133	N	Intel® HD Graphics 530	Y	65W
ntel® Core™ i3-6100 rocessor	2	3.7	N/A	3	2133	N	Intel® HD Graphics 530	N	51W

¹The specifications shown in this column represent the maximum turbo frequency with one core active. Turbo boost stepping occurs in 100MHz increments. Processors that do not have turbo functionality are denoted as N/A.



Overview

NOTES:

Integrated Intel® HD graphics P530 is supported on all Intel® Xeon® E3 processors. Intel® Xeon® E3, Intel® Core™ i3 can support either ECC or non-ECC memory; Intel® Core™ i5/i7 processors only support non-ECC memory.

* Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering is not a measurement of higher performance.

Color Space grey with black chrome accents

Convertibility The Z2 Mini G3 can either be placed flat on the desktop or mounted behind a display* or under a desk.

* Additional HP Hardware is needed for the VESA Mount for the display.

Expansion Slots 1 80mm M.2 slot (PCIe Gen3 x4) (see system board section 1 30mm M.2 slot (PCIe Gen3 x1)*

for more details)

* For WLAN/BT M.2 module only

Expansion Bays (see system board section for

more details)

Front I/O Power button

Slide I/O 1 USB 3.0 Charging Data Port, 1 USB 3.0 data port, combo headset/microphone port

1 internal 2.5" bay (for For SATA HDDs & SSDs only only)

Rear I/O **Z2 Mini Entry:** 3 DisplayPort[™] (DP 1.2) outputs from Intel® HD graphics, 2 USB 3.0 ports, 1 serial port

(optional), RJ-45 (LoM)

Z2 Mini Performance¹: 4 DisplayPort™ (DP 1.2) outputs from NVIDIA® Quadro® M620 graphics, 2 USB

3.0 ports, 2 USB 3.1 G1 Type-C™ ports, 1 serial port (optional),RJ-45 (LoM)

NOTE 1: Capable of supporting 6 displays. 6 display solution is achieved using a combination of Intel®

HD graphics and NVIDIA Quadro® graphics is ONLY supported on Windows 10.

Chassis Dimensions

(HxWxD)

Standard desktop orientation: 58 x 216 x216 mm (2.28 x 8.5 x 8.5 in)

Weight Exact weights depend upon configuration;

> Minimum Weight: 2.04 kg (4.50 lb) Typical Weight*: 2.08 kg (4.59 lb) Maximum Weight: 2.11 kg (4.65 lb)

Max Supported Weight (desktop orientation): 35 kg (77 lb)

* Configured with 1 2.5" hard drive, 1 PCIe SSD, WLAN module, 2 DIMMs and 1 NVIDIA® Quadro® graphics

card

Temperature Operating: 40° to 95°F (5° to 35°C)

Non-operating: -40° to 140°F (-40° to 60°C)

Notes: Derate the maximum operating temperature by one degree C (1.8 degrees F) for every 305m

(1,000 ft) altitude over 1,524m (5,000 ft).

Humidity Operating: 8% to 85%



Overview

Non-operating: 8% to 90%

Maximum Altitude (non-pressurized)

Operating: 3,000 m (10,000 ft) Non-operating: 9,100 m (30,000 ft).

Power Supply

Z2 Mini G3 Entry:

135W 88% Efficiency at 115Vac

Z2 Mini G3 Performance:

200W 89% Efficiency at 230Vac

NOTES: Customers placing their system in an enclosure should design their solution to accommodate

the size of the external power supply for the Z2 Mini

Chipset Intel® C236 chipset

Memory 2 SODIMM slots, supporting up to 32GB ECC/non-ECC, DDR4 2133 MT/s

The CPUs determine the speed at which the memory is clocked. If a 2133 MT/s capable CPU is used in the system, the maximum speed the memory will run at is 2133 MT/s regardless of the specified speed of the memory.

Note: Transfer rates up to 2133 MT/s

Workstation ISV See the latest list of certifications at

Certifications http://www.hp.com/united-states/campaigns/workstations/partnerships.html



Supported Components

Processors		Factory Configured	Option Kit
	Intel® Xeon® processor E3-1200 v5 family		
	Inte® Xeon® E3-1205v6 3.0 8M GT2 4C CPU	Υ	N
	Intel® Xeon® E3-1225v6 3.3 8M GT2 4C CPU	Υ	N
	Intel® Xeon® E3-1245v6 3.7 8M GT2 4C CPU	Υ	N
	Intel® Xeon® E3-1225 v5 3.3 2133 4C CPU ¹	Υ	N
	Intel® Xeon® E3-1245 v5 3.5 2133 4C CPU¹	Υ	N
	7th generation Intel® Core™ processor family		
	Intel® Core™ i5-7500 3.4 6M 4C CPU	Υ	N
	Intel® Core™ i7-7700 3.6 8M 4C CPU	Υ	N
	Intel® Core™ i3-7100 3.9 3M 2C CPU	Υ	N
	6th generation Intel® Core™ processor family		
	Intel® Core™ i7-6700 3.4 2133 4C CPU³	Υ	N
	Intel® Core i5-6500 3.2 2133 4C CPU ³	Υ	N
	6th generation Intel® Core™ i3/Pentium processor family		
	Intel® Core™ i3-6100 3.7 2133 2C CPU²	Υ	N

NOTE 1: Only supported on Z2 Mini Performance Base Unit **NOTE 2**: These processor support either ECC or non-ECC memory **NOTE 3**: These processors support only non-ECC memory

NOTE: Intel® Integrated Graphics P530 for Xeon® processors supports workstation-specific graphics drivers for improved compatibility and performance on select professional applications, compared to Intel® HD Graphics 530.

Monitors / Displays		Factory Configured	Option Kit	Option Kit Part Number
	HP DreamColor Z24x Professional Display HP DreamColor Z27x Professional Display HP Z22n Narrow Bezel IPS Display HP Z23n Narrow Bezel IPS Display HP Z24n Narrow Bezel IPS Display HP Z24nf Narrow Bezel IPS Display HP Z24nq Narrow Bezel IPS Display HP Z24s IPS UHD 4K Display HP Z25n Narrow Bezel IPS Display HP Z27n Narrow Bezel IPS Display HP Z27n Narrow Bezel IPS Display			
Notes	Supported by all Operating Systems available from HP Screen Size Diagonally Measured			



Supported Components

SATA Hard Drives		Factory Configured	Option Kit	Option Kit Part Number
	500GB SATA 7200 rpm 6Gb/s SFF HDD	Υ	Υ	TOK73AA
	1TB SATA 7200 rpm 6Gb/s SFF HDD	Υ	Υ	TOK74AA
SATA Solid State Drives	HP 256GB SATA 6Gb/s SSD	Υ	Υ	A3D26AA

PCIe SSDs	PCIe SSDs for HP Workstations	Factory Configured	Option Kit	Option Kit Part Number
	HP Z Turbo Drive G2 256GB MLC (Z2 Mini)	Υ	Υ	Y7B58AA
	HP Z Turbo Drive G2 256GB TLC (Z2 Mini)	Υ	Υ	Y7B60AA
	HP Z Turbo Drive G2 512GB MLC (Z2 Mini)	Υ	Υ	Y7B58AA
	HP Z Turbo Drive G2 1TB MLC (Z2 Mini)	Υ	Υ	1MK25AA
	** Installed in native M.2 slot on Z2 Mini motherboard			

The HP Z Turbo Drive G2 (NVMe) is not supported with Windows 7 32-bit.

Windows 10.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows 10) of system disk is reserved for system recovery software.

Graphics		Factory Configured	Option Kit	Option Kit Part Number	Supported # of cards
Integrated Graphics	Integrated Intel® HD Graphics (Z2)				
	Intel® HD Graphics P630	Υ	N		1
	Intel® HD Graphics P530	Υ	N		1
	Intel® HD Graphics 530	Υ	N		1
	Intel® HD Graphics 630	Υ	N		1
Discrete Graphics	NVIDIA® Quadro® M620 2GB Graphics¹	Υ	N		1
Graphics DisplayPort™	HP Short 34cm DisplayPort™ Cable Kit	N	Υ	1FN83AA	
Cable Adapters	HP DisplayPort™ To DVI-D Adapter	N	Υ	FH973AA	
	HP DisplayPort™ To VGA Adapter	Υ	Υ	AS615AA	
	HP DisplayPort™ to Dual Link DVI Adapter	N	Υ	NR078AA	
Notes	NOTE 1: Only offered on Z2 Mini Performance NOTE: Intermixing integrated Intel® HD graph three displays can be enabled using the Componly discrete graphics when four or more disp	nics and discret outer (F10) Seti	up Utility. Ho	wever, HP recom	mends using



achieved using a combination of Intel® HD graphics and NVIDIA Quadro® graphics is ONLY supported on

Supported Components

Memory

DDR4-2400 ECC Unbuffered SODIMMs - CTO

HP 8GB (1x8GB) DDR4-2400 ECC RAM HP 16GB (2x8GB) DDR4-2400 ECC RAM HP 32GB (2x16GB) DDR4-2400 ECC RAM

DDR4-2400 non-ECC Unbuffered SODIMMs - CTO

HP 4GB (1x4GB) DDR4-2400 nECC RAM HP 8GB (2x4GB) DDR4-2400 nECC RAM HP 8GB (1x8GB) DDR4-2400 nECC RAM HP 16GB (2x8GB) DDR4-2400 nECC RAM HP 32GB (2x16GB) DDR4-2400 nECC RAM

NOTES: Intel® Xeon® E3, Intel® Core™ i3 and Intel® Pentium® processors can support either ECC or non-ECC memory; Intel® Core™ i5/i7 processors only support non-ECC memory.

Two channels of DDR4 memory are supported. To realize full performance at least one DIMM must be inserted into each channel.

The CPUs determine the speed at which the memory is clocked. If a 2133 MT/s capable CPU is used in the system, the maximum speed the memory will run at is 2133 MT/s regardless of the specified speed of the memory.

Transfer rates up to 2133 MT/s with Intel Skylake processors.

AMO	Option Kit Part Number
DDR4-2400 ECC Unbuffered DIMMs - AMO	
HP 8GB (1x8GB) DDR4-2400 ECC RAM	Y7B56AA
HP 16GB (1x16GB) DDR4-2400 ECC RAM	Y7B53AA
HP 4GB (1x4GB) DDR4-2400 non-ECC RAM	Y7B55AA
HP 8GB (1x8GB) DDR4-2400 non-ECC RAM	Y7B57AA
HP 16GB (1x16GB) DDR4-2400 non-ECC RAM	Y7B54AA

NOTE: Only unbuffered DDR4 DIMMs are supported.

Multimedia and Audio Devices		Factory Configured	Option Kit	Option Kit Part Number
	Integrated Realtek HD ALC221-VB Audio	Υ	N	
Optical and Removable		Factory		Option Kit Part
Storage		Configured	Option Kit	Number
	HP SlimTray Optical Drives			
	HP External Ultra-Slim DVD-RW Drive	N	Υ	Y3T76AA



Supported Components

Actual speeds may vary. Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.

With Blu-ray, certain disc, digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD movies cannot be played on this workstation.

Networking and Communications		Factory Configured	Option Kit	Option Kit Part Number
	Integrated Intel® I219LM PCIe GbE Controller (Intel® vPro™ with Intel AMT 11.0)	Υ	N	
	Intel® 8265 Wireless LAN (802.11ac) and Bluetooth® 4.2 Module	Υ	N	

NOTE 1: The integrated network connection is required to support Intel® vPro™ Technology.

NOTE 2: If AMT is provisioned, then network teaming with the integrated LAN port is not possible.

NOTE 3: "Gigabit" Ethernet indicates compliance with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/sec. For high speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

Racking and Physical Security		Factory Configured	Option Kit	Option Kit Part Number
	HP Keyed Cable Lock 10mm	N	Y	T1A62AA
Input Devices		Factory Configured	Option Kit	Option Kit Part Number
	HP USB 1000dpi Laser Mouse	Υ	Υ	QY778AA
	HP USB Optical Mouse	Υ	Υ	QY777AA
	HP USB CCID SmartCard Keyboard	Υ	Υ	BV813AA
	HP USB Business Slim Keyboard	Υ	Υ	N3R87AA
	HP Wireless Business Slim Keyboard	Υ	Υ	QY449AA

Other Hardware		Factory Configured	Option Kit	Option Kit Part Number
	HP Serial Port Adapter	Υ	N	PA716A
	HP Z2 Mini VESA Sleeve	N	Υ	Y7B61AA
	Z2 Mini Z Display VESA Mount Solution - Current Displays	N	Υ	N6N00AA*
	Z2 Mini Z Display VESA Mount Solution - Legacy Displays	N	Υ	E5J35AA**

^{*} Current: "n" displays. This mounting kit supports the following displays:

Z22n/Z23n/Z24n/Z25n/Z27n, /Z24nf/Z24nq/Z24s/Z27q/Z32s/Z32x/HC240/HC270/E240c/E272.

Supported Components

** Legacy: "I" displays. This mounting kit supports the following displays: Z24i/Z27i/Z30i, /Z30i/Z24x/Z27x.

Software		Factory Configured	Option Kit	Support Notes
	Intel® Unite™	Υ	N	
	HP Performance Advisor	Υ	N	See Note 1
	HP Remote Graphics Software (RGS) 7.1	Υ	N	
	HP PC Hardware Diagnostics UEFI	Υ	N	See Note 2
	HP Client Security Software	Υ	N	
	NOTE 1: Supports, and preinstalled with Windows http://www.hp.com/go/performanceadvisor NOTE 2: Windows OS only	10 only. Also available	as a free down	load from

Operating Systems

Windows 10 Pro 64

Windows 10 Pro License MSNA

Windows 7 Professional 64(available through downgrade rights from Windows 10 Pro 64)

Red Hat® Enterprise Linux® (RHEL) Workstation - Paper License (1yr)

See http://www.microsoft.com/windows/windows-7/for support details.

See http://www.redhat.com/rhel/desktop/

Remote Power On

Benefits of the Remote Power:

- Make it easier to power-on Antman by USB keyboard/mouse in some use scenarios.
- Support wired/wireless, USB low speed/full speed keyboards and mousses.
- Easy setup in BIOS menu.
- Support waking from both S4 (Hibernate) and S5 (Shutdown).

Limitations:

- Support only at USB charging port which is the only port supplying USB power in S4/S5.
- Waking from S4/S5 is limited to only via keyboard/mouse device.

Instructions:

- 1. Connect USB keyboard/mouse to USB charging port.
- System must recognize USB keyboard/mouse in SO first. (USB full speed keyboard/mouse, such as wireless keyboard/mouse or Smart card keyboard need to connect to system over 60 seconds in SO to be recognized.)
- 3. Sleep to S4 or S5.
- 4. Wake system by any key on keyboard or clicking/movement* on mouse.



^{*} If mouse has the capability to wake system by movement

System Technical Specifications

System Board

System Board Form

Entry: 200mm x 200mm (7.9 x 7.9 inches)

Factor

Performance: 200mm x 200mm (7.9 x 7.9 inches)

Processor Socket

Single LGA 1151

CPU Bus Speed

DMI link between CPU & PCH: Performance comparable to PCIe Gen3 x4

Chipset

Intel® PCH C236

Memory Expansion Slots 2 SODIMM DDR4 memory slots

Memory Type Supported DDR4, UDIMM (Unbuffered), ECC & non-ECC

Memory Modes

Non-Interleaved for single channel. Interleaved when both channels are populated.

Memory Speed Supported 2133MHz DDR4 for Skylake processors; pre-enabled for 2400 MHz DDR4

Memory Protection

ECC available on data

*Requires ECC DIMMs to be installed, as well as a CPU that supports ECC

Maximum Memory

32**GB**

Memory Configuration

(Supported)

4GB, 8GB and 16GB non-ECC/8GB and 16GB ECC unbuffered DIMMs are supported.

ECC and non-ECC memory DIMMs cannot be mixed on the same system.

Notes

Maximum memory capacities assume 64-bit operating systems, such as Windows® 7 Professional 64-

Bit or Red Hat Linux 64-bit.

Supported Drive Interfaces

SATA

Integrated (1) Serial ATA interfaces (6Gb/s SATA).

Integrated Graphics

Intel® HD Graphics 530 (on Core™ i3/i5/i7-6xxx processors);

Intel® HD Graphics P530 for Xeon® E3 processors based on Unified

Memory Architecture (UMA).

A region of system memory is reserved and dedicated to the graphics

display.

Support for Microsoft DirectX 12.1, OpenGL 4.4 and OpenCL 2.0 on Intel®

HD Graphics P530.

(3) DP 1.2 graphics ports integrated on motherboard; Supports up to

three simultaneous displays across DP outputs. Max. resolution supported: 4096x2160 @60Hz

Integrated Ethernet PHY Connection I219LM. Management capabilities: **Network Controller**

WOL, PXE 2.1 and AMT 11.0

Serial 1 rear port (configurable option)

IEEE 1394 Connector(s)



System Technical Specifications

USB Connector(s) Front Side I/O:

2 USB 3.0 Type-A

Rear 2 USB 3.0 Type-A

2 USB 3.1 G1 Type-C[™] (Z2 Mini Performance only)

HD Integrated Audio

Yes: supports CTIA headset

Flash ROM

Chassis Fan Header Yes

Additional CPU/GFX Cooler (Z2 Mini Performance only)

Front Control

Side I/O: Yes

Panel/Speaker Header

CMOS Battery Holder -

Lithium

Yes

Yes

Integrated Trusted Platform Module

Integrated TPM 2.0

Power Supply Headers

Yes, single DC-in jack for external power supplies

Power Switch, Power LED 1. The power and failure LED are combined in the front power switch.

& Hard Drive LED Header

2. The HDD LED & DC-in LED are combined within one port on the Rear I/O. The LED will be lit once the AC power is plugged in. As soon as the system is booted up, the LED will function as a standard HDD

activity LED.

Clear Password Jumper Kevboard/Mouse

Yes USB

Power Supply

Z2 Mini G3 Entry: 135W, 88% efficiency, wide-ranging, active PFC Power Supply

Z2 Mini G3 Performance: 200W, 89% efficiency, wide-ranging, active PFC Power Supply

The Z2 Mini PSU Efficiency Report can be found at this link: TBD

Operating Voltage Range 115-230 VAC

Rated Voltage Range 100-240 VAC

Rated Line Frequency 50-60 Hz

Operating Line Frequency 47-63 Hz

Range

Rated Input Current Z2 Mini G3 Entry: 1.9A @ 90Vac

Z2 Mini G3 Performance: 2.9A @ 90Vac

Heat Dissipation Typical: TBD btu/hr (TBD kcal/hr)

Maximum: TBD btu/hr (TBD kcal/hr)

ENERGY STAR® qualified Yes

(Config Dependent)

FEMP Standby Power

Compliant

Yes, with Wake-on-LAN disabled: <1W in S5- Power Off

Surge Tolerant Full Ranging Power Supply Yes

System Technical Specifications

(withstands power surges up to 2000V)

System Configurations

Z2 Mini Configuration Processor Info

#1

Processor Info 1x Intel® Xeon® E3-1245v5 3.5 8M GT2 4C Memory Info 32GB (2x16GB) DDR4-2400 ECC SO-DIMM

ENERGY STAR QUALIFIED

Graphics Info NVIDIA® Quadro® M620 GPU

Disks/Optical/Floppy 1x 1TB 7200 RPM SATA HDD / 1x Z Turbo Drive G2 512GB PCIe 1st SSD

Power Supply 200W EPS

Other Ethernet Capable

Energy Consumption (Watts)

	115 VAC		230	VAC	100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows long Idle (S0)	23.6	51 W	23.01 W		22.95 W	
Windows short Idle (S0)	25.2	24 W	25.	2 W	25.56 W	
Windows Busy Typ(S0)	112.	64 W	4 W 112.76 W		113.67 W	
Windows Busy Max (S0)	157.	71 W	155.	95 W	159.22 W	
Sleep (S3)	2.52 W	2.47 W	2.55 W	2.47 W	2.51 W	2.5 W
Off (S5)	1.27 W	1.25 W	1.36 W	1.24 W	1.34 W	1.25 W
Zero Power Mode (ErP)	0.31 W		0.33 W		0.31 W	

Heat Dissipation (Btu/hr)

	115 VAC		230	VAC	100	VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled	
Windows long Idle (S0)	80.56	btu/hr	78.51	btu/hr	78.31 btu/hr		
Windows short Idle (S0)	86.12	btu/hr	85.99	btu/hr	87.21	87.21 btu/hr	
Windows Busy Typ(S0)	384.34	384.34 btu/hr 384.75 btu/hr		btu/hr	387.86 btu/hr		
Windows Busy Max (S0)	538.13	btu/hr	532.12	ttu/hr	543.28 btu/hr		
Sleep (S3)	8.6 btu/hr	8.43 btu/hr	8.7 btu/hr	8.43 btu/hr	8.56 btu/hr	8.53 btu/hr	
Off (S5)	4.33 btu/hr	4.27 btu/hr	4.64 btu/hr	4.23 btu/hr	4.57 btu/hr	4.27 btu/hr	
Zero Power Mode (ErP)	1.06 t	otu/hr	1.13 btu/hr 1.06 t		btu/hr		

Z2 Mini Configuration Memory Info#2 Graphics Info

Processor Info 1x Intel® Xeon® E3-1225v5 3.3 8M GT2 4C Memory Info HP 8GB (2x4GB) DDR4-2400 ECC SO-DIMM

Graphics Info NVIDIA® Quadro® M620 GPU Disks/Optical/Floppy 1x 1TB 7200 RPM SATA HDD

Power Supply 200W EPS
Other Ethernet Capable

Energy Consumption (Watts)

	115 VAC		230	VAC	100	VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
Windows long Idle (S0)	19.	2 W	19.8	35 W	19.	19.62 W	
Windows short Idle (S0)	21.9	12 W	22.1	18 W	21.	21.73 W	
Windows Busy Typ(S0)	96.0	12 W	94.19 W		97.	97.79 W	
Windows Busy Max (S0)	141.	.2 W	142.	16 W	140.6 W		
Sleep (S3)	1.78 W	1.7 W	1.83 W	1.75 W	1.79 W	1.71 W	
Off (S5)	1.16 W	1.14 W	1.2 W	1.19 W	1.16W	1.14 W	
Zero Power Mode (ErP)	0.3	1 W	0.35 W 0.31		31 W		



System Technical Specifications

Heat Dissipation (Btu/hr)

	115	115 VAC		VAC	100 VAC		
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled	
Windows long Idle (S0)	65.51	65.51 btu/hr		67.73 btu/hr		66.95 btu/hr	
Windows short Idle (S0)	74.79	btu/hr	75.68 btu/hr		74.15 btu/hr		
Windows Busy Typ(S0)	327.63	327.63 btu/hr		321.39 btu/hr		333.67 btu/hr	
Windows Busy Max (S0)	481.79	btu/hr	485.07	' btu/hr	479.75 btu/hr		
Sleep (S3)	6.07 btu/hr	5.8 btu/hr	6.24 btu/hr	5.97 btu/hr	6.11 btu/hr	5.83 btu/hr	
Off (S5)	3.96 btu/hr	3.89 btu/hr	4.1 btu/hr	4.06 btu/hr	3.96 btu/hr	3.89 btu/hr	
Zero Power Mode (ErP)	1.06 l	1.06 btu/hr		1.19 btu/hr		1.06 btu/hr	

Z2 Mini Configuration Processor Info

ENERGY STAR QUALIFIED

1x Intel® Core™ i7-6700 3.4 8M 4C

32GB (2x16GB) DDR4-2400 nECC SO-DIMM Memory Info

Graphics Info Intel® HD Graphics 530

Disks/Optical/Floppy 1x 1TB 7200 RPM SATA HDD / 1x Z Turbo Drive G2 512GB PCIe 1st SSD

Power Supply 135W EPS Other **Ethernet Capable**

Energy Consumption (Watts)

	115	115 VAC		VAC	100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows long Idle (S0)	12.9	98 W	13.18 W		13.02 W	
Windows short Idle (S0)	13.5	52 W	13.8	32 W	13.6	57 W
Windows Busy Typ(S0)	96.	96.2 W 98.06 W		99.	99.7 W	
Windows Busy Max (S0)	105.	74 W	105.	85 W	103.7 W	
Sleep (S3)	2.29 W	2.24 W	2.35 W	2.34 W	2.3 W	2.27 W
Off (S5)	1.25 W	1.22 W	1.37 W	1.33 W	1.41 W	1.37 W
Zero Power Mode (ErP)	0.27 W		0.32 W		0.27 W	

Heat Dissipation (Btu/hr)

	115 VAC		230	VAC	100 VAC		
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled	
Windows long Idle (S0)	44.29	44.29 btu/hr		btu/hr	44.43 btu/hr		
Windows short Idle (S0)	46.13	btu/hr	47.16 btu/hr		46.64	46.64 btu/hr	
Windows Busy Typ(S0)	328.25	btu/hr	334.59 btu/hr		340.19 btu/hr		
Windows Busy Max (S0)	360.8	btu/hr	361.18	btu/hr	353.84 btu/hr		
Sleep (S3)	7.81 btu/hr	7.64 btu/hr	8.02 btu/hr	7.98btu/hr	7.85 btu/hr	7.75 btu/hr	
Off (S5)	4.27 btu/hr	4.16 btu/hr	4.67 btu/hr	4.54 btu/hr	4.81 btu/hr	4.67 btu/hr	
Zero Power Mode (ErP)	0.92	btu/hr	1.09 btu/hr 0.92 btu/hr		btu/hr		

Z2 Mini Configuration Processor Info

ENERGY STAR

QUALIFIED

1x Intel® Core™ i3-6100 3.7 3M 2C

Memory Info

32GB (2x16GB) DDR4-2400 nECC SO-DIMM

Graphics Info Disks/Optical/Floppy NVIDIA® Quadro® M620 GPU

1x 1TB 7200 RPM SATA HDD / 1x Z Turbo Drive G2 512GB PCIe 1st SSD

200W EPS Power Supply

Other Ethernet Capable

Energy Consumption (Watts)

	115 VAC		230	VAC	100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows long Idle (S0)	22.92 W		22.42 W		22.51 W	
Windows short Idle (S0)	24.4	12 W	23.6	55 W	23.95 W	
Windows Busy Typ(S0)	79.3	39 W	80.34 W 77.93 V		93 W	
Windows Busy Max (S0)	118.	18 W	118.24 W		119.18 W	



System Technical Specifications

Sleep (S3)	2.49 W	2.47 W	2.48 W	2.48 W	2.49 W	2.45 W
Off (S5)	1.48 W	1.14 W	1.3 W	1.13 W	1.29 W	1.26 W
Zero Power Mode (ErP)	0.3	1 W	0.33	3 W	0.3	1 W

Heat Dissipation (Btu/hr)

	115	115 VAC		230 VAC		VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled	
Windows long Idle (S0)	78.21	btu/hr	76.5 l	76.5 btu/hr		76.81 btu/hr	
Windows short Idle (S0)	83.32	btu/hr	80.7 l	otu/hr	81.72 btu/hr		
Windows Busy Typ(S0)	270.89	270.89 btu/hr		274.13 btu/hr		265.91 btu/hr	
Windows Busy Max (S0)	403.25	btu/hr	403.45	btu/hr	406.66 btu/hr		
Sleep (S3)	8.5 btu/hr	8.43 btu/hr	8.46 btu/hr	8.46 btu/hr	8.5 btu/hr	8.36 btu/hr	
Off (S5)	5.05btu/hr	3.89 btu/hr	4.44 btu/hr	3.86 btu/hr	4.4 btu/hr	4.3 btu/hr	
Zero Power Mode (ErP)	1.06 l	1.06 btu/hr		1.13btu/hr		1.06 btu/hr	

Z2 Mini Configuration Processor Info#5 Memory Info

Processor Info 1x Intel® Core™ i3-6100 3.7 3M 2C

Memory Info 4GB (1x4GB) DDR4-2400 nECC SO-DIMM

Graphics Info Intel® HD Graphics 530
Disks/Optical/Floppy 1x 1TB 7200 RPM SATA HDD

Power Supply 135W EPS
Other Ethernet Capable

Energy Consumption (Watts)

	115 VAC		230	VAC	100	VAC
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows long Idle (S0)	13.2	26 W	10.5	58 W	12.05 W	
Windows short Idle (S0)	14.8	34 W	12.99 W		12.39 W	
Windows Busy Typ(S0)	64.0	06 W	65.23 W		64.26 W	
Windows Busy Max (S0)	87.9	97 W	92.1	15 W	88.17 W	
Sleep (S3)	1.8 W	1.67 W	1.87 W	1.77 W	1.78 W	1.66 W
Off (S5)	1.19 W	1.18 W	1.27 W	1.26 W	1.17 W	1.15 W
Zero Power Mode (ErP)	0.31 W 0.37W		7W	0.31 W		

Heat Dissipation (Btu/hr)

	115 VAC		230	VAC	100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled
Windows long Idle (S0)	45.24 btu/hr		36.1 t	otu/hr	41.12 btu/hr	
Windows short Idle (S0)	50.64	btu/hr	44.32	btu/hr	42.28 btu/hr	
Windows Busy Typ(S0)	218.58	3 btu/hr	222.57btu/hr		219.26 btu/hr	
Windows Busy Max (S0)	300.17	7 btu/hr	314.43	btu/hr	300.85 btu/hr	
Sleep (S3)	6.14 btu/hr	5.7 btu/hr	6.38 btu/hr	6.04 btu/hr	6.07 btu/hr	5.66 btu/hr
Off (S5)	4.06 btu/hr	4.03 btu/hr	4.33 btu/hr	4.3 btu/hr	3.99 btu/hr	3.92 btu/hr
Zero Power Mode (ErP)	1.06	btu/hr	1.26 btu/hr		1.06 btu/hr	

Deskside Sound Pressure

Deskside Sound Pressure

QuickSpecs

System Technical Specifications

Declared Noise Emissions Z2 Mini (Entry)

Declared Noise Emissions (Entry-level and High-end configurations)

System ConfigurationProcessor InfoIntel® Core™ i3-6100 QJZG/3.7G/4M/2c(Entry level With HDD)Memory Info1 - 4GB DDR4-2400 SO-DIMM Memory

Graphics Info iGfx

Disks/SSD 1 - Hitachi 500GB SATA 7200RPM HDD

1 - Samsung 256GB PCIe M.2 SSD

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)

(LWAd, bels) (LpAm, decibels)

Idle 3.08 16.2

Hard drive Operating 3.08 17.1

(random reads)

Sound Power

System Configuration (Entry level Only SSD)

Processor Info Intel® Core™ i3-6100 QJZG/3.7G/4M/2c

Memory Info 1 - 4GB DDR4-2400 SO-DIMM Memory

Graphics Info iGfx

Disks/SSD N / A

1 - Samsung 256GB PCle M.2 SSD

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)

(LWAd, bels) (LpAm, decibels)

Idle 2.97 11.7

Hard drive Operating / /
(random reads)

Sound Power

System Configuration (High-end)

Processor InfoIntel® Core™ i7-6700 QJE9/3.4G/8M/4cMemory Info2 - 8GB DDR4-2400 SO-DIMM Memory

Graphics Info iGfx

Disks/SSD 1 - Hitachi 1TB SATA 7200RPM HDD 1 - Samsung 512GB PCIe M.2 SSD

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)

Sound Power (LWAd, bels)

Idle 3.14
Hard drive Operating Sound Pressure (LWAd, bels)

Outpart (LpAm, decibels)

19.2

19.4

(random reads)

Declared Noise Emissions Z2 Mini Performance

Declared Noise Emissions (Entry-level and High-end configurations)

System ConfigurationProcessor InfoIntel® Core™ i3-6100 SR2HG/3.7G/4M/2c(Entry level With HDD)Memory Info1 - 4GB DDR4-2400 SO-DIMM Memory

Graphics Info NVIDIA Quadro / N17

Disks/SSD 1 - Hitachi 500GB SATA 7200RPM HDD

1 - Samsung 256GB PCle M.2 SSD

Sound Power (LWAd, bels) Deskside Sound Pressure (LpAm, decibels)



QuickSpecs

System Technical Specifications

Declared Noise Emission		3.16	20.3
(in accordance with ISO 7779 and ISO 9296)	Hard drive Operating (random reads)	3.17	20.4
System Configuration	Processor Info	Intel® Core™ i3-6100 SR2HG/3.7G/4M/2c	
(Entry level Only SSD)	Memory Info	1 - 4GB DDR4-2400 SO-DIMM Memory	

Graphics Info

NVIDIA Quadro / N17 Disks/SSD N/A

1 - Samsung 256GB PCle M.2 SSD **Declared Noise Emissions Sound Power**

Deskside Sound Pressure (in accordance with ISO (LWAd, bels) (LpAm, decibels) 7779 and ISO 9296) Idle 3.06 19.1 **Hard drive Operating** / /

(random reads) **System Configuration Processor Info** Intel Xeon E3-1245v5 QJ70/3.5G/8M/4c (High-end) 2 - 8GB DDR4-2400 SO-DIMM Memory **Memory Info**

(random reads)

Graphics Info NVIDIA Quadro / N17 Disks/SSD 1 - Hitachi 1TB SATA 7200RPM HDD 1 - Samsung 512GB PCle M.2 SSD

Declared Noise Emissions Sound Power Deskside Sound Pressure (in accordance with ISO (LWAd, bels) (LpAm, decibels) 7779 and ISO 9296) Idle 3.21 22.2 **Hard drive Operating** 3.23 22.7

System Technical Specifications

Environmental Requirements

Temperature Operating: 40° to 95° F (5° to 35° C)

Non-operating: -40° to 140° F (-40° to 60° C)

Humidity Operating: 8% to 85% RH, non-condensing

Non-operating: 8% to 90% RH, non-condensing

Maximum Altitude Operating: 10,000 feet (3,000 m)

Non-operating: 30,000 feet (9,100 m)

Dynamic (new) Shock

Operating: 1/2-sine: 40g, 2-3ms

Non-operating:

1/2-sine: 160 cm/s, 2-3ms (~100g)

square: 422 cm/s, 20g

Vibration

Operating random: 0.5g (rms), 5-300 Hz Non-operating random: 2.0g (rms), 10-500 Hz

Notes: Values represent individual shock events and do not indicate repetitive shock events. Values do not indicate continuous vibration.

Cooling Above 5,000 ft (1524 m) altitude, maximum operating temperature is de-

rated by 1.8° F (1° C) per 1,000 ft (305 m) elevation increase



System Technical Specifications

Physical Security and Serviceability

Access Panel Tool-less

Includes system board and memory information

Hard Drives HDD cage requires the use of a screwdriver to remove the HDD

Expansion Cards M.2 module requires a screwdriver to service and replace.

Processor Socket Tool-less, except for the processor heatsink.

Color-coordinated Cables Yes

and Connectors

Memory Tool-less

System Board Screw-In

Dual Color Power and HD The Power LED is on the front of the system, but the HDD LED is located on the Rear of the system

LED on Front of Computer

Configuration Record SW Yes

Over-Temp Warning on

Screen

Yes

Restore CD/DVD Set Consists of an operating system DVD (OSDVD) and a driver DVD (DRDVD). OSDVD restores the original

operating system. DRDVD will provide all drivers for the system. The DRDVD may also contain applications that originally shipped with the system for optional installation. Applications can also be obtained from HP.com. OSDVD and DRDVD are orderable with the system and available from HP

Support.

Dual Function Front

Power Switch

Yes, causes a fail-safe power off when held for 4 seconds (default) or 15 seconds (can be configured by

F10 BIOS setup\Advanced\System Options\Power button override)

Cable Lock Support

Yes, Kensington Cable Lock (optional): Locks top cover from being opened and secures chassis to

furniture to prevent theft

3 mm x 7 mm slot at rear of system

Serial, Parallel, USB, Audio, Network, Enable/Disable Port

Control

Yes, enables or disables serial, USB, audio, and network ports (parallel port is not supported on the Z2

Mini G3)

Removable Media Write/Boot Control Yes, prevents ability to boot from removable media on supported devices (and can disable writes to

media)

Power-On Password Yes, prevents an unauthorized person from booting up the workstation

Setup Password Yes, prevents an unauthorized person from changing the workstation configuration



System Technical Specifications

NIC LEDs (integrated) (Green & Amber)

Yes

CPUs and Heatsinks

A T-15 Torx or flat blade screwdriver is needed to remove the CPU heatsink before the CPU can be

removed. CPU removal is tool-less

Power Supply Diagnostic Yes; this is located on the Rear of the chassis and combined with the HDD LED.

When the PSU adapter is plugged in, and the unit is powered off, the Power OK LED will glow.

Front Power LED Yes, white (normal), red (fault)

Internal Speaker Yes, on the side of the chassis

System/Emergency ROM

Flash Recovery

Recovers corrupted system BIOS.

Cooling Solution Air cooled forced convection

CPU Heatsink Fan Z2 Mini Entry & Performance CPU blower solution: 11.1 mm x 65mm x 82.1mm

Z2 Mini Performance GPU blower solution: 29mm x 103.6mm x 102.2mm

Chassis Fan Z2 Mini G3 Entry: Single system blower

Z2 Mini G3 Performance: Dual system blower

Memory Heatsink Fan No

HP PC Hardware Diagnostics UEFI HP PC Hardware Diagnostics (UEFI) enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing F2 at POST, and is available as a

download from HP Support.

The Kensington lock slot on the chassis serves this purpose **Access Panel Key Lock**

ACPI-Ready Hardware

Advanced Configuration and Power Management Interface (ACPI). • Allows the system to wake from a low power mode.

Controls system power consumption, making it possible to place individual cards and peripherals in a

low-power or powered-off state without affecting other elements of the system

Trusted Platform Module Yes

Chip

M.2 Card Retention Yes, all M.2 modules are retained by a single screw

Flash ROM Yes

Diagnostic Power Switch Yes

LED on board

Clear Password Jumper Yes

Clear CMOS Jumper Yes



System Technical Specifications

CMOS Battery Holder Yes: Z2 Min iG3 Entry

Yes: Z2 Mini G3 Performance

DIMM Connectors Yes

BIOS

BIOS 32-bit Services Standard BIOS 32-bit Service Directory Proposal v0.4

PCI 3.0 Support Full BIOS support for PCI Express through industry standard interfaces.

ATAPI ATAPI Removable Media Device BIOS Specification Version 1.0.

BIOS Boot Specification v1.01.

Provides more control over how and from what devices the workstation will boot.

WMI Support WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is

fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM)

and WBEM specifications.

BIOS Power On Users can define a specific day-of-week and time for the system to power on.

ROM Based Computer Setup Utility (F10) Review and customize system configuration settings controlled by the BIOS.

System/Emergency ROM Flash Recovery with

Video

Recovers system BIOS in corrupted Flash ROM.

Replicated Setup Saves BIOS settings to USB flash device in human readable file. Repset.exe utility can then replicate

these settings on machines being deployed without entering Computer Configuration Utility (F10

Setup).

SMBIOS System Management BIOS 2.7.1, for system management information.

Boot Control Disables the ability to boot from removable media on supported devices.

Memory Change Alert Alerts management console if memory is removed or changed.

Thermal Alert Monitors the temperature state within the chassis. Three modes:

• NORMAL - normal temperature ranges.

• ALERTED - excessive temperatures are detected. Raises a flag so action can be taken to avoid

shutdown or provide for a smoother system shutdown.

SHUTDOWN - excessive temperatures are encountered. Automatically shuts down the computer

without warning before hardware component damage occurs.

Remote ROM Flash Provides secure, fail-safe ROM image management from a central network console.

Updates can be performed before starting the OS.

Updates can be periodically scheduled.



System Technical Specifications

ACPI (Advanced

Allows the system to enter and resume from low power modes (sleep states).

Management Interface)

Configuration and Power Enables an operating system to control system power consumption based on the dynamic workload. Makes it possible to place individual cards and peripherals in a low-power or powered-off state without

affecting other elements of the system.

Supports ACPI 4.0 for full compatibility with 64-bit operating systems.

Ownership Tag

A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen.

Remote Wakeup/Remote System administrators can power on, restart, and power off a client computer from a remote location.

Shutdown

ASF 2.0 Compliant

Yes.

Instantly Available PC (Suspend to RAM - ACPI sleep state S3)

Allows for very low power consumption with quick resume time.

Remote System Installation via F12 (PXE 2.1) (Remote Boot from Server)

Allows a new or existing system to boot over the network and download software, including the

operating system.

ROM revision levels

Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is available through an industry standard interface (SMBIOS) so that management SW applications can

use and report this information.

System board revision

level

Allows management SW to read revision level of the system board.

Revision level is digitally encoded into the HW and cannot be modified.

Start-up Diagnostics (Power-on Self-Test) Assesses system health at boot time with selectable levels of testing.

Auto Setup when new hardware installed

System automatically detects addition of new hardware.

Keyboard-less Operation The system can be booted without a keyboard.

Common BIOS image supports System Configuration Utility (F10 Setup) menus in 12 languages with **Localized ROM Setup**

local keyboard mappings.

Asset Tag The user or IT administrator to set a unique tag string in non-volatile memory.

Per-slot Control Allows I/O slot parameters (option ROM enable/disable) to be configured individually.

Adaptive Cooling Control parameters are set according to detected hardware configuration for optimal acoustics.

Pre-boot Diagnostics (Pre-video) critical errors are reported via beeps and blinks on the power LED.

Digitally and BIOS

Helps to prevent the installation of unauthorized versions of a BIOS (a roque BIOS) from a virus, **Cryptographically Signed** malware, or other code that could lead to compromised system security, data access, physical service,

or even system board replacement.



System Technical Specifications

Master Boot Record Protection

A feature in the HP BIOS that prevents changes and/or infections to the Master Boot Record. Useful in protecting from viruses.

Boot Block Emergency Recovery Mode (BIOS Recovery) The HP BIOS offers a write-protected boot block ROM that provides recovery from a failed flashing of the computer BIOS. This special recovery mode prevents the system from becoming unusable or "bricked" when a BIOS update is interrupted.

Industry Standard Specification Support

Industry Standard Revision Supported by the BIOS

UEFI Specification Revision

UEFI 2.4.0

ACPI Advanced Configuration and Power Management Interface, Version 4.0

ASF Alert Standard Format Specification, Version 2.0

EDD - Enhanced Disk Drive Specification Version 1.1

- BIOS Enhanced Disk Drive Specification Version 3.0

PCI Express PCI Express Base Specification, Revision 2.0;

PCI Express Base Specification, Revision 3.0.

PMM POST Memory Manager Specification, Version 1.01

SATA - Serial ATA Specification, Revision 1.0a

Serial ATA II: Extensions to Serial ATA 1.0, Revision 1.0a
 Serial ATA II Cables and Connectors Volume 2 Gold

- SATA-IO SATA Revision 3.0 Specification

SPD PC SDRAM Serial Presence Detect (SPD) Specification, Revision 1.2B

TPM Trusted Computing Group TPM Specification Version 2.0

USB Universal Serial Bus Revision 1.1 Specification

Universal Serial Bus Revision 2.0 Specification Universal Serial Bus Revision 3.0 Specification

System Technical Specifications

Social and Environmental Responsibility

Declarations

Eco-Label Certifications & This product is low halogen except for power cords, cables and peripherals. Service parts obtained after purchase may not be Low Halogen.

- ENERGY STAR® (energy-saving features available on selected configurations –Windows® only)
- US Federal Energy Management Program (FEMP)
- China Energy Conservation Program (CECP)
- IT ECO declaration

Batteries

The battery in this product complies with EU Directive 2006/66/EC

Battery size: CR2032 (coin cell) Battery type: Lithium Metal

The battery in this product does not contain:

- Mercury greater than 5ppm by weight
- Cadmium greater than 10ppm by weight
- Lead greater than 40ppm by weight

Restricted Material Usage This product meets the material restrictions specified in HP's General Specification for the Environment. http://www.hp.com/hpinfo/qlobalcitizenship/environment/pdf/qse.pdf

HP Inc. is committed to compliance with all applicable environmental laws and regulations, including the European Union Restriction of Hazardous Substances (RoHS) Directive. HP's goal is to exceed compliance obligations by meeting the requirements of the RoHS Directive on a worldwide basis. This product is low halogen except for power cords, cables and peripherals, as well as the following customer-configurable internal components: Creative Recon3D PCIe Audio Card is not Low Halogen.

Service parts obtained after purchase may not be Low Halogen.

Low Halogen Statement

End-of-Life Management and Recycling

HP Inc. Corporate Environmental Information

HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. This product is greater than 90% recyclable by weight when properly disposed of at end of life. For more information about HP's commitment to the environment:

Living Progress Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www.hp.com/hpinfo/globalcitizenship/environment/productdesign/ecolabels.html

ISO 14001 certificates:

http://www.hp.com/hpinfo/globalcitizenship/environment/operations/envmanagement.html

Additional Information

- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC.
- Plastic parts weighing over 25 grams used in the product are marked per ISO 11469 and IS01043.
- This product is >90% recycle-able when properly disposed of at end of life
- EPEAT® Gold registered in the U.S. EPEAT registration varies by country. See http://www.epeat.net for registration status by country.

Packaging

HP Workstation product packaging meets the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/society/gen_specifications.html

Does not contain restricted substances listed in HP Standard 011-1 General Specification for the Environment

System Technical Specifications

- Does not contain ozone-depleting substances (ODS)
- Does not contain heavy metals (lead, mercury, cadmium or hexavalent chromium) in excess of 100 ppm sum total for all heavy metals listed
- Maximizes the use of post-consumer recycled content materials in packaging materials
- All packaging material is recyclable
- All packaging material is designed for ease of disassembly
- Reduced size and weight of packages to improve transportation fuel efficiency
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards formatting

Packaging Materials Internal

External

Cushions made from fabricated recycled expanded-polyethylene (EPE) or recycled expanded-polypropylene (EPP). May also be made from recycled molded paper-pulp (MPP). Carton made from corrugated fiberboard with at least 25% recycled content.



System Technical Specifications

Manageability

Intel® Active Management The HP Z2 Mini G3 workstation supports Intel® vPro™ technology when purchased with a vPro™

Technology (AMT) technology capable CPU: Intel® Xeon® processor family or 6th Generation Intel® Core™ i5/i7 processors

with Intel® VT-d/VT-x and Intel® TXT technology.

Remote Manageability Software Solutions

Visit: http://www.hp.com/go/easydeploy

System Software Manager Service, Support, and Warranty Visit: http://www.hp.com/go/ssm

- Program to proactively communicate Product Change Notifications (PCNs) and Customer Advisories by email to customers, based on a user-defined profile.
- PCNs provide advance notification of hardware and software changes to be implemented in the factory providing time to plan for transition.
- Customer Advisories provide concise, effective problem resolution, greatly reducing the need to call technical support.

Stable & Consistent Offerings

As part of its commitment to hardware, software, and solution innovation, HP is proud to introduce this breakthrough platform configuration stability to HP Workstation customers. HP Stable & Consistent Offerings are built on the foundation of a carefully chosen set of hardware and software designed and tested to work with all HP Z Workstation platforms through their end of life. These components and their corresponding HP Workstation platform compatibility are outlined in this section.

HP Stable & Consistent Offerings are available worldwide to all HP Workstation customers-no special programs, no additional cost, no kidding. Simply select your hardware and software components when you customize your HP Workstation and be assured that you'll be able to buy that same configuration throughout the lifecycle of the product.

Processors	Product # X8V05AV	Offering Intel® Xeon® E3- 1225v5 3.3GHz CPU			
	X8V06AV	Intel® Xeon® E3- 1245v5 3.5GHz CPU			
Hard Drives	Product #	Offering			
	X8U91AV	HDD 500GB 7200RPM SATA 2.5			
	X8U90AV	HDD 1TB 7200RPM SATA 2.5			
Memory	Product #	Offering			
	X8V29AV	RAM 8GB (1x8GB) DDR4 2400 ECC Unbuffered			
	X8V24AV	RAM 16GB (2x8GB) DDR4 2400 ECC Unbuffered			



Technical Specifications - Processors

Intel® Xeon® processor E3-1200 v5 family

Intel® Xeon® E3-1245 v5 3.5 2133 4C CPU Intel® Xeon® E3-1225 v5 3.3 2133 4C CPU

Intel® Core™ i7-6700 3.4 2133 4C CPU Intel® Core™ i5-6500 3.2 2133 4C CPU

Intel® Core™ i3-6100 3.7 2133 2C CPU



Technical Specifications - Hard Drives

SATA Hard Drives for I	HP			
Workstations				

500GB SATA 7200 rpm 6Gb/s 3.5" HDD

Capacity 500GB **Protocol** SATA **Form Factor** SFF (2.5") Controller AHCI Rated for 24/7/365 NO

operation

Physical Size (Height) 0.28 in; .7 cm Physical Size (Width) 2.75 in; 6.99 cm **Media Diameter** 2.5 in; 6.36 cm

Interface Serial ATA (6Gb/s), NCQ enabled

Up to 600MB/s

Synchronous Transfer Rate (Maximum)

Operating Temperature 32° to 140° F (0° to 60° C)

1TB SATA 7200 rpm 6Gb/s SFF HDD

Capacity 1TB SATA **Protocol Form Factor** SFF (2.5") **Controller** AHCI Rated for 24/7/365 NO operation

Physical Size (Height) 0.28 in; .7 cm Physical Size (Width) 2.75 in; 6.99 cm **Media Diameter** 2.5 in: 6.36 cm

Interface Serial ATA (6Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Operating Temperature 32° to 140° F (0° to 60° C)

Up to 600MB/s

SATA SSDs for HP Workstations

HP 256GB SATA 6Gb/s SSD

Capacity 256GB **Protocol** SATA **Form Factor** 2.5" Controller AHCI **NAND Type** MLC

Endurance 200TBW (TB Written)

Reliability (MTTF) 1.5M hours Physical Size (Height) 0.28 in; 0.7 cm Physical Size (Width) 2.5 in; 6.36 cm Interface SATA 6Gb/s **Synchronous Transfer** Up to 600MB/s

Operating Temperature

Rate (Maximum)

32° to 158° F (0° to 70° C)

Performance Sequential Read 560MB/s (max) **Sequential Write** 510MB/s (max) **Random Read**

100K IOPS (max) **Random Write** 88K IOPS (max)

Technical Specifications - Graphics

Integrated Intel® HD Graphics (Z2) **Form Factor** Integrated in select Intel® Xeon® E3, Intel® Core™ i7, Intel® Core™ i5, and

Intel® Core™ i3 processors.

Check specific platform specifications for selections.

Graphics Controller Intel® HD Graphics

Memory Unified Memory Architecture (UMA) frame buffer. Graphics memory is

shared with system memory. Size selectable between 32 MB to 1024 MB via BIOS setting. Default size is 128 MB. Additional memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (Intel®

DVMT), to provide an optimal balance between graphics and system

memory use.

Connectors Check system platform specifications where Intel® HD Graphics are

available.

Maximum Resolution DisplayPort™ 1.2:

- up to 4096x2160 x 30 bpp @ 60Hz

- supports High Bit Rate 2 (HBR2) and Multi-Stream Transport (MST)

HDMI 2.0 output:

- up to 4096x2160 x 30 bpp @ 60Hz

Dual Link DVI(I) output:

- up to 2560 x 1600 x 32 bpp @ 60Hz

Single Link-DVI(I) output:

- up to 1920 x 1200 x 32 bpp @ 60Hz

VGA output:

- 2048 × 1536 × 32 bpp @ 85 Hz

Note: For HDMI, DVI, and VGA outputs, separate adapters required.

Shading Architecture Shader Model 5.0 Supported Graphics APIs OpenGL 4.0

DirectX 11.1

Available Graphics Windows 10
Drivers Windows 7

*Integrated graphics will depend on processor. HD content required to view HD images

Technical Specifications - Graphics

NVIDIA® Quadro® M620 2GB Graphics **Maximum Resolution** DisplayPort 1.2:

- up to 4096x2160 x 30 bpp @ 60Hz

- supports High Bit Rate 2 (HBR2) and Multi-Stream Transport (MST)

HDMI 2.0 output:

- up to 4096x2160 x 30 bpp @ 60Hz

Image Quality Features Stereoscopic 3D display support including NVIDIA® 3D Vision™ technology,

3D DLP, Interleaved, and passive stereo

Display Output Maximum number of displays:

- 4 direct attached monitors

Maximum number of DisplayPort™ displays possible per DisplayPort™ output (Multiple displays daisy-chained from one DisplayPort™ 1.2 port requires DisplayPort™ 1.2 MST capable displays or DP1.3 MST capable

hub):

- 4 1920x1200 @ 60 Hz - 2 2560x1600 @ 60 Hz - 1 4096x2160 @ 60 Hz

Maximum number of monitors across all available Quadro M620 outputs is

4.

Supported Graphics APIs OpenGL 4.5

DirectX 12

API support includes:

CUDA C, CUDA C++, DirectCompute 5.0, OpenCL, Java, Python, and Fortran

Available Graphics Drivers Microsoft Windows 10 Microsoft Windows 7

Linux - Full OpenGL implementation, complete with NVIDIA and ARB

extensions

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html



Technical Specifications - Optical and Removable Storage

HP External Ultra-Slim DVD-RW Drive

Description External 9.5mm high, tray-load **Mounting Orientation** Either horizontal or vertical

Interface Type USB 2.0

Dimensions (WxHxD) 144 x 14 x 137.5mm

Supported Media Types DVD-RAM

DVD+R DVD+RW DVD+R DL DVD-R DL DVD-R DVD-RW CD-R CD-RW

Disc CapacityDVD-ROM8.5 GB DL or 4.7 GB standardAccess TimesFull Stroke DVD160ms (typical for Random Stroke)Full Stroke CD140ms (typical for Random Stroke)

Maximum Data Transfer CD ROM Read CD-ROM, CD-R Up to 24X

Rates

CD-RW Up to 24X

DVD ROM Read DVD-RAM Up to 8X DVD+RW Up to 8X

DVD-RW Up to 8X
DVD+R DL Up to 8X
DVD-R DL Up to 8X
DVD-ROM Up to 8X
DVD-ROM DL Up to 8X
DVD-ROM DL Up to 8X
DVD+R Up to 8X
DVD-R Up to 8X

Power Source USB 2.0 DC power

DC Power Requirements 5 VDC ± 5%-100 mV ripple p-p

DC Current 5 VDC -< 800 mA typical, <1600 mA maximum

Operating Environmental Temperature 41° to 104° F (5° to 40° C)

(all conditions non-condensing) Relative Humidity 15% to 80%

Maximum Wet Bulb 84° F (29° C)

Temperature

Operating Systems
Supported

Windows 10 32-bit and 64-bit, Windows 8 32-bit and 64-bit, Windows 7 Professional 32-bit and 64-bit, Windows Vista Business 64*, Windows Vista Business 32*, Windows Vista Home Basic 32*, Windows 2000, Windows XP

Professional or Windows XP Home 32*.

Red Hat Enterprise Linux(RHEL) WS4**, 5, 6 Desktop/Workstation,

Removed reference to "Novell" because of acquisition and changed product

reference to "SUSE Linux Enterprise Desktop 10 & 11",

No driver is required for this device. Native support is provided by the

operating system.

Kit Contents HP External Ultra-Slim DVD-RW Drive DVD Writer drive, USB 2.0 type A to

mini-B cable.

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Technical Specifications - Optical and Removable Storage

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Technical Specifications - Networking and Communications

Integrated Intel® I219LM Connector **PCIe GbE Controller** (Intel® vPro™ with Intel® **AMT 11.0)**

RJ-45

Controller Intel® I219LM GbE platform LAN connect networking controller

Memory 3 KB Tx and 3KB Rx FIFO packet buffer memory

Data Rates Supported 10/100/1000 Mbps

Compliance 802.1as/1588, 802.1p, 802.1Q, 802.3, 802.3ab, 802.3az, 802.3i, 802.3u,

802.3z

Bus Architecture PCI Express and SMBus

Data Transfer Mode PCIe-based interface for active state operation (SO state) and SMBus for

host and management traffic (Sx low power state)

Requires 3.3V (integrated regulators for core Vdc) **Power Requirement**

Boot ROM Support Yes

Network Transfer Mode Full-duplex; Half-duplex (not supported for the 1000BASE-T transceiver)

Network Transfer Rate 10BASE-T (half-duplex) 10 Mbps

10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps

Management Capabilities vPro, WOL, auto MDI crossover, PXE, iSCSI Boot, Muti-port teaming, RSS,

ACPI, Advanced cable diagnostic, loopback modes,

AMT 11.0 support, Circuit Breaker, VLAN, Multicast Listener Discovery

(MLD)

Intel® 8265 Wireless LAN Connector (802.11ac) and Bluetooth Controller 4.2 Module

Compliance

M.2 (Supports 2230 form factor; E Key) Motherboard Interface

Intel® Dual Band Wireless-AC 8260

Wireless LAN: IEEE 802.11abgn, 802.11ac, 802.11d, 802.11e, 802.11i,

802.11h, 802.11w, CCX 4.x/CCX Lite, WMM, WPA, WPA2, APS, WPS 2.0,

Protected Management Frames

Bluetooth®: Dual Mode Bluetooth® 2.1, 2.1+EDR, 3.0, 4.0, BLE, and 4.2

Bus Architecture PCI Express Gen3 x1 and USB 2.0 **Power Requirement** Requires 3.3V; 1.65W TDP

Management Capabilities Wake on WLAN (in all sleep states, excluding Max Power Savings mode),

WFA Management Frame Protection (802.11w), vPro/WiAMT Not Currently Supported, F10 BIOS Menu option to disable/enable WLAN and Bluetooth® radios, supports seamless roaming between 802.11 wireless access points

Throughput Max PHY throughput 887 Mbps (802.11ac) for WLAN

Technical Specifications - Other Hardware

HP Z2 Mini VESA Sleeve	Mechanical	Dimensions (H x W x D)	Unpackaged	70 mm x 224 mm x 223 mm (2.75 x 8.81 x 8.77 in)
			Packaged	-
		Weight	Unpackaged	1.7 kg (3.7 lb)
			Packaged	-
	Other	Option kit contents	HP Z2 Mini VESA Sleeve, mounting screws, installation guide, warranty card.	
	Limited Warranty			• • • • • • • • • • • • • • • • • • • •



Summary of Changes

Date of change:	Version History:		Description of change:	
January 1, 2017	From v1 to v2	Added	Remote Power On feature in Supported components; Declared noise emissions in System Technical Specifications.	
March 1, 2017	From v2 to v3	Added	7 th Gen Intel processors, Intel HD Graphics 630, bottom view and disc, mounting kits for displays.	
April 1, 2017	From v3 to v4	Added	Intel HD Graphics P630 Intel Xeon v6 processors, HP Short 34cm DisplayPort Cable Kit	
		Changed	NVIDIA M620 from Entry 3D to Discrete Graphcis	
		Removed	Factory configured flag to DP to DVI-D adapters in Cable adapters section	
May 1, 2017	From v4 to v5	Added	Added the HP Z Turbo Drive G2 1TB SSD to PCIe SSDs section, added the HP Z2 Mini VESA Sleeve to Other Hardware section, added the Intel® Unite™ into Software section.	
June 1, 2017	From v5 to v6	Added	Windows 10 Pro License MSNA to Operating Systems section	



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